

# GENERAL INFORMATION, INSTRUCTIONS, AND DEFINITIONS FOR COMMISSION FOREIGN PRODUCER/EXPORTER QUESTIONNAIRES

# DRAMS AND DRAM MODULES FROM KOREA Investigation No. 701-TA-431 (Preliminary)

<u>Further information.</u>--If you have any questions concerning the enclosed questionnaire(s) or other matters related to this investigation, you may contact the following member of the Commission's staff (Fax 202-205-3205):

Mary Messer, investigator (202-205-3193; E-mail MMESSER@USITC.GOV)

# **GENERAL INFORMATION, INSTRUCTIONS, AND DEFINITIONS**

#### **GENERAL INFORMATION**

**Background**.--This investigation was instituted in response to a petition filed on November 1, 2002, by Micron Technology, Inc., Boise, ID. Countervailing duties may be assessed on the subject imports as a result of this investigation if the Commission makes an affirmative determination of injury, threat, or material retardation, and if the U.S. Department of Commerce makes an affirmative determination of subsidization.

Additional questionnaires will be supplied promptly upon request, or photocopies of the enclosed questionnaire(s) may be used. Address all correspondence to the United States International Trade Commission, Washington, DC 20436. Hearing-impaired individuals can obtain information regarding this investigation via the Commission's TDD terminal (202-205-1810).

<u>Due date of questionnaire(s)</u>.--Return the completed questionnaire(s) to the United States International Trade Commission by no later than November 15, 2002. Although the enclosed postpaid envelope may be used to return the completed questionnaire, use of an overnight mail service may be necessary to ensure that your response actually reaches the Commission by November 15, 2002. If you do not use the enclosed envelope, please make sure the completed questionnaire is sent to the attention of Mary Messer, room 615-J. Return <u>only one</u> copy of the completed questionnaire(s), but please keep a copy for your records so that you can refer to it if the Commission staff contacts you with any questions during the course of the investigation.

<u>Service of questionnaire response(s)</u>.--In the event that your firm is a party to this investigation, you are required to serve a copy of the questionnaire(s), once completed, on parties to the proceeding that are subject to administrative protective order (see 19 CFR § 207.7). A list of such parties is maintained by the Commission's Secretary and may be obtained by calling 202-205-1803. A certificate of service must accompany the copy of the completed questionnaire(s) you submit (see 19 CFR § 207.7).

<u>Confidentiality</u>.--The commercial and financial data furnished in response to the enclosed questionnaire(s) that reveal the individual operations of your firm will be treated as confidential by the Commission to the extent that such data are not otherwise available to the public and will not be disclosed except as may be required by law (see 19 U.S.C. § 1677f). Such confidential information will not be published in a manner that will reveal the individual operations of your firm; however, nonnumerical characterizations of numerical business proprietary information (such as discussion of trends) will be treated as confidential business information only at the request of the submitter for good cause shown.

# GENERAL INFORMATION, INSTRUCTIONS, AND DEFINITIONS--Continued

#### **GENERAL INFORMATION--Continued**

<u>Verification</u>.--The information submitted in the enclosed questionnaire(s) is subject to audit and verification by the Commission. To facilitate possible verification of data, please keep all your workpapers and supporting documents used in the preparation of the questionnaire response(s).

**Release of information**.--The information provided by your firm in response to the questionnaire(s), as well as any other business proprietary information submitted by your firm to the Commission in connection with the investigation, may become subject to, and released under, the administrative protective order provisions of the Tariff Act of 1930 (19 U.S.C. § 1677f) and section 207.7 of the Commission's Rules of Practice and Procedure (19 CFR § 207.7). This means that certain lawyers and other authorized individuals may temporarily be given access to the information for use in connection with this investigation or other import-injury investigations conducted by the Commission on the same or similar merchandise; those individuals would be subject to severe penalties if the information were divulged to unauthorized individuals.

#### **INSTRUCTIONS**

<u>Answer all questions</u>.--Do not leave any question or section blank unless a questionnaire expressly directs you to skip over certain questions or sections. If the answer to any question is "none," write "none." If information is not readily available from your records in exactly the form requested, furnish carefully prepared estimates--designated as such by the letter "E"--and explain the basis of your estimates. Answers to questions and any necessary comments or explanations should be supplied in the space provided or on separate sheets attached to the appropriate page of the questionnaire(s). If your firm is completing more than one questionnaire in connection with this investigation (i.e., a producer, importer, purchaser, and/or foreign producer questionnaire), you need not respond to duplicated questions in the questionnaires.

<u>Consolidate all establishments in Korea</u>.--Report the requested data for your establishment(s) located in Korea. Firms operating more than one establishment should combine the data for all establishments into a single report.

# GENERAL INFORMATION, INSTRUCTIONS, AND DEFINITIONS--Continued

#### **DEFINITIONS**

<u>DRAMs</u>.--Dynamic random access memory semiconductors, whether assembled (cased) or unassembled (uncased), as defined below, classifiable in subheading 8542.21.80 of the 2002 Harmonized Tariff Schedule of the United States (HTS).<sup>1</sup> DRAMs include, but are not limited to, synchronous DRAM (SDRAM), double data rate synchronous DRAM (DDR SDRAM), fast page-mode (FPM) DRAM, extended-data-out (EDO) DRAM, burst extended-data-out (BEDO) DRAM, "Rambus" DRAM (RDRAM), video RAM (VRAM), Windows RAM (WRAM), and synchronous graphics RAM (SGRAM). Not included are DRAMs re-imported for repair or replacement.

<u>Uncased DRAMs</u>.--Processed silicon wafers, uncut dice, and cut dice, that are not encapsulated in plastic, ceramic, or other materials, as covered by 2002 HTS statistical reporting number 8542.21.8005.<sup>2</sup>

<u>Cased DRAMs</u>.--Processed and cut silicon dice that are encapsulated in plastic, ceramic, or other materials, as covered by 2002 HTS statistical reporting numbers 8542.21.8021 through 8542.21.8029.<sup>3</sup>

<u>DRAM modules</u>.--A collection of DRAMs, the sole function of which is memory, classifiable in HTS subheading 8473.30.10. Modules include single in-line packages ("SIPs"), single in-line memory modules (SIMMs), dual in-line memory modules (DIMMs), small outline dual in-line memory module (SODIMMs), Rambus memory modules, memory cards or other collections of DRAMs whether mounted or unmounted on a circuit board. Modules that contain other parts that are needed to support the function of memory are included. Only those modules that contain additional items that alter the function of the module to something other than memory, such as video graphics adapter (VGA) boards and cards, are not included. Also not included are DRAM modules re-imported for repair or replacement.<sup>4</sup>

<u>**DRAM densities.**</u>--The following definitions should be applied: 1 kilobit=1,024 bits; 1 megabit=1,048,576 bits; 8 bits=1 byte; and 1 billion bits=1,000,000,000 bits.

<u>Die or dice</u>.--A unit(s) on a wafer separated by scribe lines; after all of the wafer fabrication steps are completed, die or dice are separated by sawing.

<u>3<sup>rd</sup> sources or 3<sup>rd</sup> countries</u>.--All foreign locations <u>except</u> Korea, i.e., all locations other than the United States and Korea

**8-inch-equivalent wafers**—Wafers should be reported on an 8-inch-equivalent basis using the following conversions: if you produce 6-inch wafers, you should multiply your total by 0.5625 and if you produce 12-inch wafers, you should multiply your total by 2.25.

<sup>&</sup>lt;sup>1</sup> In the 1999-2001 HTS, the subheading was 8542.13.80.

<sup>&</sup>lt;sup>2</sup> During 1999-2001, the statistical reporting number was 8542.13.8005.

<sup>&</sup>lt;sup>3</sup> During 1999-2000, the statistical reporting numbers were 8542.13.8021 through 8542.13.8034; in 2001, the statistical reporting numbers were 8542.13.8012 through 8542.13.8032.

<sup>&</sup>lt;sup>4</sup> Also included are removable DRAM modules placed on motherboards, with or without a central processing unit, if the importer or a related party or a party controlled by the importer removes the modules from the motherboards after importation.

# GENERAL INFORMATION, INSTRUCTIONS, AND DEFINITIONS--Continued

#### **DEFINITIONS**--Continued

#### Subject Korean DRAMs and DRAM modules:

#### **Subject Korean DRAMs**:

<u>Subject Korean uncased DRAMs</u>.--Uncased DRAMs fabricated in Korea, <u>Subject Korean cased DRAMs</u>.--Cased DRAMs made from Korean fabricated dice (regardless of where assembled), and cased DRAMs assembled in Korea (regardless of where the dice are fabricated), and

<u>Subject Korean DRAM modules</u>.--DRAM modules that are made from subject Korean DRAMs, as defined above.

# **U.S.-produced DRAMs and DRAM modules:**

#### *U.S.-produced DRAMs*:

<u>U.S.-produced uncased DRAMs</u>.--Uncased DRAMs fabricated in the United States,

<u>U.S.-produced cased DRAMs</u>.--Cased DRAMs made from U.S.-fabricated dice assembled anywhere in the world <u>except</u> Korea<sup>5</sup> plus cased DRAMs assembled in the United States from dice fabricated in 3<sup>rd</sup> sources (as defined above),

<u>U.S.-produced DRAM modules</u>.--DRAM modules that are made from U.S.-produced DRAMs, as defined above.<sup>6</sup>

# Nonsubject foreign (3<sup>rd</sup>-source) DRAMs and DRAM modules:

# *Nonsubject foreign (3<sup>rd</sup>-source) DRAMs*:

**Nonsubject foreign (3<sup>rd</sup>-source) uncased DRAMs**.--Uncased DRAMs fabricated in 3<sup>rd</sup> sources.

*Nonsubject foreign (3<sup>rd</sup>-source) cased DRAMs*.--Cased DRAMs assembled in 3<sup>rd</sup> sources from 3<sup>rd</sup>-source fabricated dice,<sup>7</sup>

*Nonsubject foreign (3<sup>rd</sup>-source) DRAM modules*.--DRAM modules that are made from 3<sup>rd</sup>-source DRAMs, as defined above.<sup>8</sup>

<u>To case</u>.—Assembly of uncased DRAMs into cased DRAMs. E.g., in these questionnaires, the term "cased in Korea" is synonymous with "assembled into cased DRAMs in Korea."

<sup>&</sup>lt;sup>5</sup> Note that cased DRAMs assembled in Korea from U.S. fabricated dice are <u>NOT</u> considered to be U.S.-produced product and are instead included in subject Korean cased DRAMs.

<sup>&</sup>lt;sup>6</sup> Note that modules made from U.S.-fabricated dice that were assembled into cased DRAMs in Korea are <u>NOT</u> considered to be U.S.-produced product and are instead included in <u>subject Korean DRAM modules</u>.

<sup>&</sup>lt;sup>7</sup> Note that cased DRAMs assembled in Korea from 3<sup>rd</sup>-source fabricated dice are <u>NOT</u> considered to be 3<sup>rd</sup>-source product and are instead included in <u>subject Korean cased DRAMs</u>; likewise, cased DRAMs assembled in the United States from 3<sup>rd</sup>-source fabricated dice are <u>NOT</u> considered to be 3<sup>rd</sup>-source product and are instead included in U.S.-produced cased DRAMs.

<sup>&</sup>lt;sup>8</sup> Note that modules made from 3<sup>rd</sup>-source fabricated dice that were assembled into cased DRAMs in Korea (regardless of where assembled into modules) are <u>NOT</u> considered to be 3<sup>rd</sup>-source product and are instead included in <u>subject Korean DRAM modules</u>; likewise, modules made from 3<sup>rd</sup>-source fabricated dice that were assembled into cased DRAMs in the United States (regardless of where assembled into modules) are <u>NOT</u> considered to be 3<sup>rd</sup>-source product and are instead included in U.S.-produced product.

# GENERAL INFORMATION, INSTRUCTIONS, AND DEFINITIONS -- Continued

#### **DEFINITIONS--Continued**

**Firm**.--An individual proprietorship, partnership, joint venture, association, corporation (including any subsidiary corporation), business trust, cooperative, trustee in bankruptcy, or receiver under decree of any court.

**Related firm**.--A firm that your firm solely or jointly owned, managed, or otherwise controlled; a firm that solely or jointly owned, managed, or otherwise controlled your firm; and/or a firm that was solely or jointly owned, managed, or otherwise controlled by a firm that also solely or jointly owned, managed, or otherwise controlled your firm.

<u>Establishment</u>.--Each facility of a firm in Korea involved in the production of DRAMs of DRAM modules (as defined above), including auxiliary facilities operated in conjunction with (whether or not physically separate from) such facilities.

<u>United States</u>.--For purposes of this investigation, the 50 States, Puerto Rico, the U.S. Virgin Islands, and the District of Columbia.

<u>Importer</u>.--Any person or firm engaged, either directly or through a parent company or subsidiary, in importing DRAMs or DRAM modules (as defined above) into the United States from a foreign manufacturer or through its selling agent.

<u>Average production capacity</u>.--The level of production that your establishment(s) could reasonably have expected to attain during the specified periods. Assume normal operating conditions (i.e., using equipment and machinery in place and ready to operate; normal operating levels (hours per week/weeks per year) and time for downtime, maintenance, repair, and cleanup; and a typical or representative product mix).

**<u>Production</u>**.--All production in your establishment(s) in Korea, including production consumed internally within your firm.

**Shipments**.--Shipments of products produced in your establishment(s) in Korea. Quantities reported should be net of returns.

*Home market commercial shipments*.--Shipments, other than internal consumption and transfers to related firms, within Korea.

*Home market internal consumption/transfers to related firms*.--Shipments made to related firms in Korea, including product consumed internally by your firm.

**Export shipments.**--Shipments to destinations outside Korea, including shipments to foreign affiliates.

*Inventories*.--Finished goods inventory, not raw materials or work-in-progress.